



Polyflon Bonding Film

Polyflon Bonding Film is a thermally stabilized, irradiated polyolefin co-polymer developed to achieve excellent bond strength with *low-flow* characteristics. The film can be used for fabricating strip-line circuits using most of today's microwave/RF laminate materials. The low bonding temperature is ideal for temperature critical materials/applications.

- Features and Benefits**
- Low Dk
 - Low Loss
 - Low Flow

Property	Value	Units	Direction	Frequency	Test Method/Condition
Thickness	.002	Inches			
Dielectric Constant	2.34	-		9.5 GHz	ASTM D-150
Dissipation Factor	.002	-		9.5 GHz	ASTM D-150
Dielectric Strength (0.002")	1000	V/mil	Z	-	ASTM D 149
Volume Resistivity	10 ¹⁶	ohm • cm	Z	-	ASTM D 257
Tensile Strength	3000 nom	psi			ASTM D-882
Elongation	300 nom	%			ASTM D-882
Specific Gravity	2.15	-	-	-	ASTM D 792
Density	0.929	gm/cm ³			ASTM D-1052
Color	Translucent				
Water Absorption	<.01	%	-	-	ASTM D 570
RoHS Compliant	Yes	Compliance Statement Available Upon Request			

Bonding Technique

1. The boards to be bonded must be clean and free from skin oils, dust and foreign matter. The dielectric surfaces should be primed with appropriate commercial preparations (e.g. Use a sodium etch treatment such as Tetra Etch to prepare PTFE based boards). Copper surfaces can be cleaned using a scrubber, however, do not make contact with primed surfaces.
2. Place bonding film between boards to be laminated. A thermocouple is recommended at the bondline.
3. Place in hot press at 100-125 psi and raise temperature of bondline to 250-300°F.
4. Hold under pressure for 6-10 minutes.
5. Cool under pressure to less than 100°F before removing from press.

<i>Polyflon Bonding Film Ordering Information</i>		
Thickness	Sheet Size*	Part Number
0.002" (51µm)	24" x 36" (610mm x 914mm)	PPBF-200

*Also available in roll form. Contact us for details

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